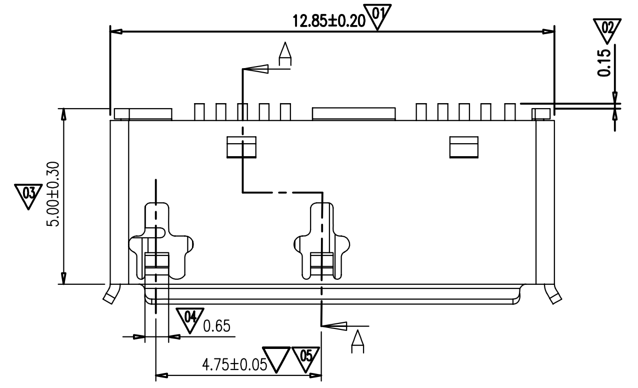
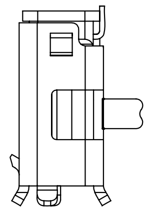
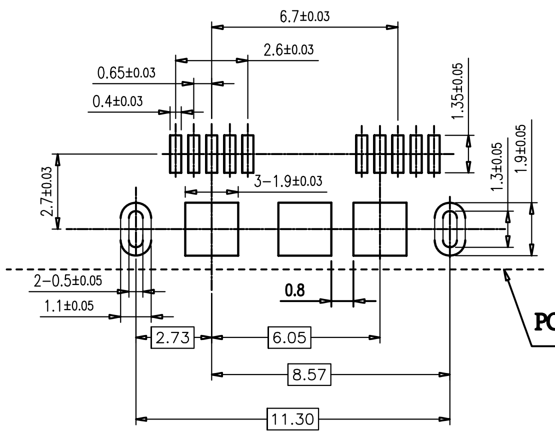
REV.	ECN. NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
				09.10.11	

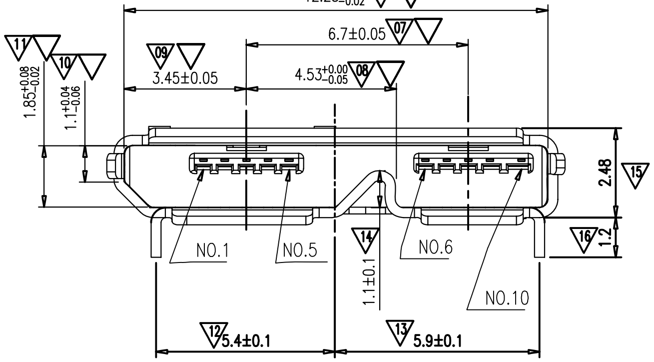
Pin Number	Signal Name
1	VBUS
2	D−
3	D+
4	ID
5	GND
6	MicB_SSTX−
7	MicB_SSTX+
8	GND_DRAIN
9	MicB_SSRX−
10	MicB_SSRX+
Shell	Shield

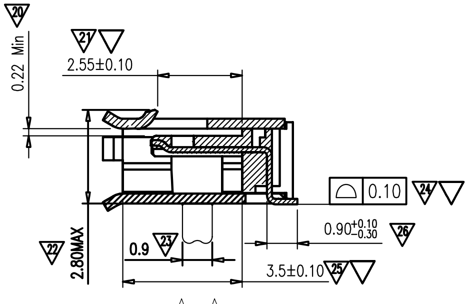






RECOMMENDED PCB LAYOUT





A−A

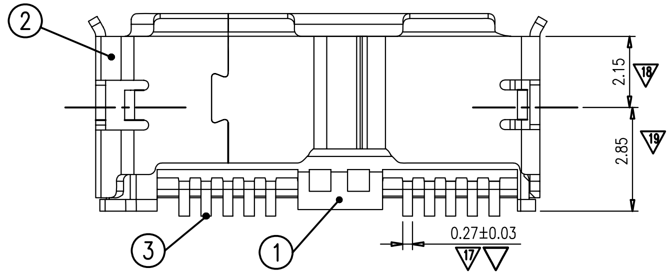
NOTES:

1. INSULATOR: LCP . COLOR−BLACK
2. USB CONTACT: BRASS.0.15mm THICKNESS,SELECTIVE GOLD. PLATED ON CONTACT AREA, GOLD FLASH PLATED ON SOLDER TAIL, 80 U" MIN. NICKEL UNDERPLATED OVERALL.
3. SHELL: STAINLESS STEEL ,0.3mm THICKNESS,GOLD FLASH PLATED ON THE SOLDERING TAB.

-0XX

Contact Finish：

01: Material
02: G/F
03：5u"Gold
04: 10u"Gold
05: 15u"Gold
06: 30u"Gold



THIRD ANGLE PROJECTION	TOLERANCES UNLESS OTHERWISE SPECIFIED:	DWN 09.11.07	BossConn Electronics
	0 PLC ± 0.30 1 PLC ± 0.25 2 PLC ± 0.20 3 PLC ± 0.15	CHK ZCD	
QUALITY SYMBOLS		APVD ZAD	MATERIAL / MODEL
▽ MUST IN QIP ▼ SHOULDED BE FAL	ANGULAR:±5°	NAME	MICRO USB 3.0-B SMT TYPE(DIP SHELL)

THIS DRAWING CONTAINS INFORMATION THAT ISPROPRIETARY TO TIANYU SEIKO ELECTRONICS TECHNOLOGY CO., LTD. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.

SCALE	SIZE	DESIGN UNITS	SHEET	REV	P/N NO.
1:1	A4	METRIC	1 OF 1	A01	−XXX